An adhesive sheet based on a siloxane-modified polyamideimide resin composition, and a CSP board and a semiconductor device produced by using the sheet

An adhesive sheet comprises a polyimide base layer and an adhesive layer (a) disposed on at least one side of the polyimide base layer, the adhesive layer (a) being a layer of a B-stage cured product of a siloxane-modified polyamideimide resin composition comprising 100 parts by weight of a siloxane-modified polyamideimide resin and 1 to 200 parts by weight of a thermosetting resin ingredient. A chip-size package board is produced by making a through-hole in the adhesive sheet, laminating a copper foil on the adhesive layer (a), forming a circuit by removing unnecessary parts of the copper foil by etching, and then gold plating a surface of the circuit. A semiconductor device is prepared by bonding a semiconductor chip to the surface of the chip-size package board bearing the circuit, connecting the circuit of the chip-size package board to bonding pads of the semiconductor chip, and sealing the circuit of the chip-size package board, the bonding wires and the semiconductor chip with a molded resin.
## DOCUMENTS CONSIDERED TO BE RELEVANT

<table>
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<tr>
<th>Category</th>
<th>Citation of document with indication, where appropriate, of relevant passages</th>
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**TECHNICAL FIELDS SEARCHED (IPC)**

- C08L
- C09J
- H01L

The present search report has been drawn up for all claims

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<tr>
<td>Munich</td>
<td>5 October 2006</td>
<td>Glanddier, Anne</td>
</tr>
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**CATEGORY OF CITED DOCUMENTS**

- T: theory or principle underlying the invention
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This annex lists the patent family members relating to the patent documents cited in the above-mentioned European search report. The members are as contained in the European Patent Office EDP file on 05-10-2006. The European Patent Office is in no way liable for these particulars which are merely given for the purpose of information.

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